

## LM741 Operational Amplifier

Check for Samples: [LM741](#)

### FEATURES

- **Overload Protection on the Input and Output**
- **No Latch-Up When the Common Mode Range is Exceeded**

### DESCRIPTION

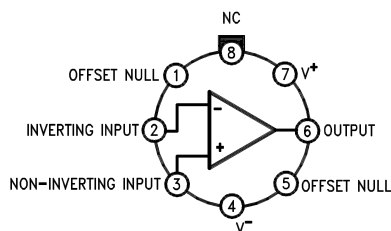
The LM741 series are general purpose operational amplifiers which feature improved performance over industry standards like the LM709. They are direct, plug-in replacements for the 709C, LM201, MC1439 and 748 in most applications.

The amplifiers offer many features which make their application nearly foolproof: overload protection on the input and output, no latch-up when the common mode range is exceeded, as well as freedom from oscillations.

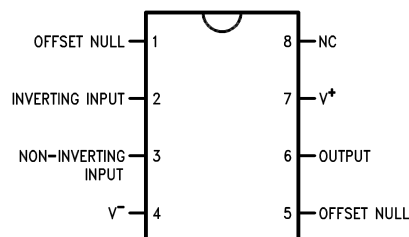
The LM741C is identical to the LM741/LM741A except that the LM741C has their performance ensured over a 0°C to +70°C temperature range, instead of –55°C to +125°C.

### Connection Diagrams

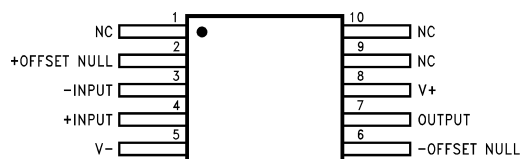
LM741H is available per JM38510/10101



**Figure 1. TO-99 Package**  
See Package Number LMC0008C



**Figure 2. CDIP or PDIP Package**  
See Package Number NAB0008A, P0008E



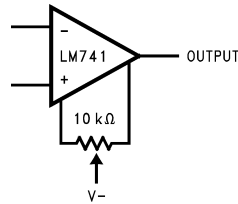
**Figure 3. CLGA Package**  
See Package Number NAD0010A



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## Typical Application



**Figure 4. Offset Nulling Circuit**



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

## Absolute Maximum Ratings<sup>(1)(2)(3)</sup>

	LM741A	LM741	LM741C
Supply Voltage	±22V	±22V	±18V
Power Dissipation <sup>(4)</sup>	500 mW	500 mW	500 mW
Differential Input Voltage	±30V	±30V	±30V
Input Voltage <sup>(5)</sup>	±15V	±15V	±15V
Output Short Circuit Duration	Continuous	Continuous	Continuous
Operating Temperature Range	-55°C to +125°C	-55°C to +125°C	0°C to +70°C
Storage Temperature Range	-65°C to +150°C	-65°C to +150°C	-65°C to +150°C
Junction Temperature	150°C	150°C	100°C
Soldering Information			
P0008E-Package (10 seconds)	260°C	260°C	260°C
NAB0008A- or LMC0008C-Package (10 seconds)	300°C	300°C	300°C
M-Package			
Vapor Phase (60 seconds)	215°C	215°C	215°C
Infrared (15 seconds)	215°C	215°C	215°C
ESD Tolerance <sup>(6)</sup>	400V	400V	400V

- (1) "Absolute Maximum Ratings" indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not ensure specific performance limits.
- (2) For military specifications see RETS741X for LM741 and RETS741AX for LM741A.
- (3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications.
- (4) For operation at elevated temperatures, these devices must be derated based on thermal resistance, and  $T_j$  max. (listed under "Absolute Maximum Ratings").  $T_j = T_A + (\theta_{JA} P_D)$ .
- (5) For supply voltages less than ±15V, the absolute maximum input voltage is equal to the supply voltage.
- (6) Human body model, 1.5 kΩ in series with 100 pF.

## Electrical Characteristics<sup>(1)</sup>

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage	$T_A = 25^\circ\text{C}$										mV
	$R_S \leq 10\text{ k}\Omega$				1.0	5.0		2.0	6.0		
	$R_S \leq 50\Omega$		0.8	3.0							
Average Input Offset Voltage Drift	$T_{AMIN} \leq T_A \leq T_{AMAX}$			4.0							$\mu\text{V}/^\circ\text{C}$
	$R_S \leq 50\Omega$										
	$R_S \leq 10\text{ k}\Omega$						6.0			7.5	

- (1) Unless otherwise specified, these specifications apply for  $V_S = \pm 15\text{V}$ ,  $-55^\circ\text{C} \leq T_A \leq +125^\circ\text{C}$  (LM741/LM741A). For the LM741C/LM741E, these specifications are limited to  $0^\circ\text{C} \leq T_A \leq +70^\circ\text{C}$ .

**Electrical Characteristics<sup>(1)</sup> (continued)**

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
Input Offset Voltage Adjustment Range	$T_A = 25^\circ\text{C}$ , $V_S = \pm 20\text{V}$	$\pm 10$						$\pm 15$			mV
Input Offset Current	$T_A = 25^\circ\text{C}$		3.0	30		20	200		20	200	nA
	$T_{AMIN} \leq T_A \leq T_{AMAX}$			70		85	500			300	
Average Input Offset Current Drift				0.5							nA/°C
Input Bias Current	$T_A = 25^\circ\text{C}$		30	80		80	500		80	500	nA
	$T_{AMIN} \leq T_A \leq T_{AMAX}$			0.210			1.5			0.8	$\mu\text{A}$
Input Resistance	$T_A = 25^\circ\text{C}$ , $V_S = \pm 20\text{V}$	1.0	6.0		0.3	2.0		0.3	2.0		M $\Omega$
	$T_{AMIN} \leq T_A \leq T_{AMAX}$ , $V_S = \pm 20\text{V}$	0.5									
Input Voltage Range	$T_A = 25^\circ\text{C}$							$\pm 12$	$\pm 13$		V
	$T_{AMIN} \leq T_A \leq T_{AMAX}$				$\pm 12$	$\pm 13$					
Large Signal Voltage Gain	$T_A = 25^\circ\text{C}$ , $R_L \geq 2\text{ k}\Omega$ $V_S = \pm 20\text{V}$ , $V_O = \pm 15\text{V}$ $V_S = \pm 15\text{V}$ , $V_O = \pm 10\text{V}$	50									V/mV
	$T_{AMIN} \leq T_A \leq T_{AMAX}$ , $R_L \geq 2\text{ k}\Omega$ , $V_S = \pm 20\text{V}$ , $V_O = \pm 15\text{V}$ $V_S = \pm 15\text{V}$ , $V_O = \pm 10\text{V}$	32									V/mV
	$V_S = \pm 5\text{V}$ , $V_O = \pm 2\text{V}$	10			25			15			
Output Voltage Swing	$V_S = \pm 20\text{V}$ $R_L \geq 10\text{ k}\Omega$ $R_L \geq 2\text{ k}\Omega$	$\pm 16$ $\pm 15$									V
	$V_S = \pm 15\text{V}$ $R_L \geq 10\text{ k}\Omega$ $R_L \geq 2\text{ k}\Omega$				$\pm 12$ $\pm 10$	$\pm 14$ $\pm 13$		$\pm 12$ $\pm 10$	$\pm 14$ $\pm 13$		V
Output Short Circuit Current	$T_A = 25^\circ\text{C}$ $T_{AMIN} \leq T_A \leq T_{AMAX}$	10 10	25	35 40		25			25		mA
Common-Mode Rejection Ratio	$T_{AMIN} \leq T_A \leq T_{AMAX}$ $R_S \leq 10\text{ k}\Omega$ , $V_{CM} = \pm 12\text{V}$ $R_S \leq 50\Omega$ , $V_{CM} = \pm 12\text{V}$	80	95		70	90		70	90		dB
Supply Voltage Rejection Ratio	$T_{AMIN} \leq T_A \leq T_{AMAX}$ , $V_S = \pm 20\text{V}$ to $V_S = \pm 5\text{V}$ $R_S \leq 50\Omega$ $R_S \leq 10\text{ k}\Omega$	86	96		77	96		77	96		dB
Transient Response	$T_A = 25^\circ\text{C}$ , Unity Gain	Rise Time	0.25	0.8		0.3			0.3		$\mu\text{s}$
		Overshoot	6.0	20		5			5		%
Bandwidth <sup>(2)</sup>	$T_A = 25^\circ\text{C}$	0.437	1.5								MHz
Slew Rate	$T_A = 25^\circ\text{C}$ , Unity Gain	0.3	0.7			0.5			0.5		V/ $\mu\text{s}$
Supply Current	$T_A = 25^\circ\text{C}$					1.7	2.8		1.7	2.8	mA
Power Consumption	$T_A = 25^\circ\text{C}$		80	150							mW
	$V_S = \pm 20\text{V}$ $V_S = \pm 15\text{V}$					50	85		50	85	

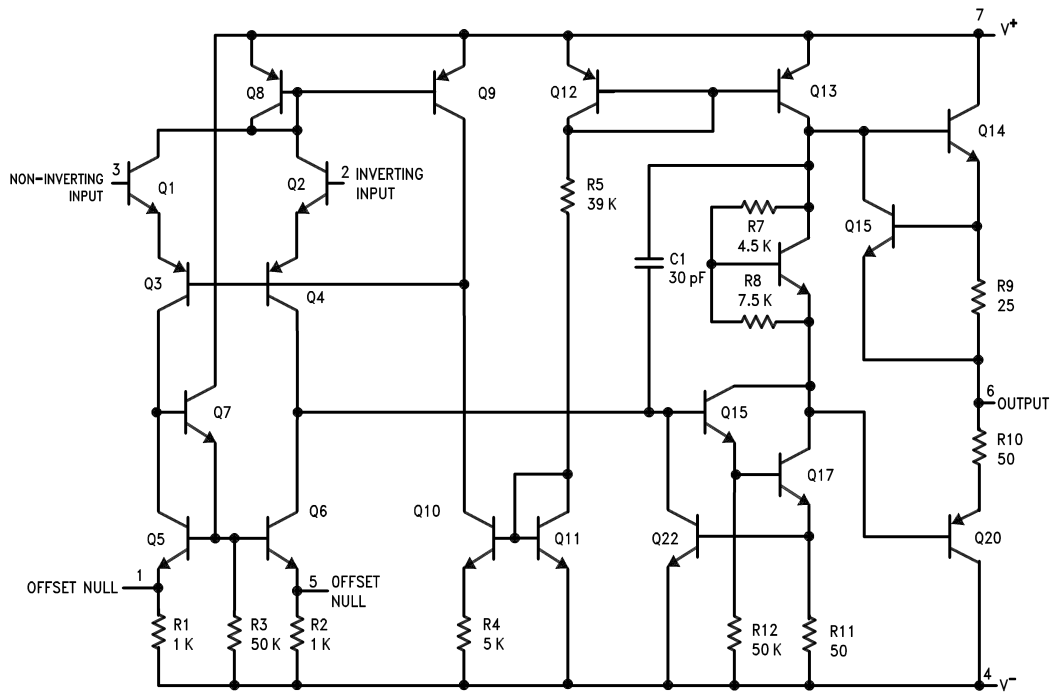
 (2) Calculated value from:  $\text{BW (MHz)} = 0.35/\text{Rise Time } (\mu\text{s})$ .

**Electrical Characteristics<sup>(1)</sup> (continued)**

Parameter	Test Conditions	LM741A			LM741			LM741C			Units
		Min	Typ	Max	Min	Typ	Max	Min	Typ	Max	
LM741A	$V_S = \pm 20V$ $T_A = T_{AMIN}$ $T_A = T_{AMAX}$			165							mW
LM741	$V_S = \pm 15V$ $T_A = T_{AMIN}$ $T_A = T_{AMAX}$					60 45	100 75				mW

Thermal Resistance	CDIP (NAB0008A)	PDIP (P0008E)	TO-99 (LMC0008C)	SO-8 (M)
$\theta_{JA}$ (Junction to Ambient)	100°C/W	100°C/W	170°C/W	195°C/W
$\theta_{JC}$ (Junction to Case)	N/A	N/A	25°C/W	N/A

**SCHEMATIC DIAGRAM**



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**REVISION HISTORY**

<b>Changes from Revision B (March 2013) to Revision C</b>	<b>Page</b>
• Changed layout of National Data Sheet to TI format .....	<a href="#">4</a>

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**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
LM741CH	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	0 to 70	LM741CH	<a href="#">Samples</a>
LM741CH/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	0 to 70	LM741CH	<a href="#">Samples</a>
LM741CN	NRND	PDIP	P	8	40	TBD	Call TI	Call TI	0 to 70	LM 741CN	
LM741CN/NOPB	ACTIVE	PDIP	P	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	0 to 70	LM 741CN	<a href="#">Samples</a>
LM741H	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	-55 to 125	LM741H	<a href="#">Samples</a>
LM741H/NOPB	ACTIVE	TO-99	LMC	8	500	Green (RoHS & no Sb/Br)	POST-PLATE	Level-1-NA-UNLIM	-55 to 125	LM741H	<a href="#">Samples</a>
LM741J	ACTIVE	CDIP	NAB	8	40	TBD	Call TI	Call TI	-55 to 125	LM741J	<a href="#">Samples</a>
U5B7741312	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	-55 to 125	LM741H	<a href="#">Samples</a>
U5B7741393	ACTIVE	TO-99	LMC	8	500	TBD	Call TI	Call TI	0 to 70	LM741CH	<a href="#">Samples</a>
U9T7741393	NRND	PDIP	P	8	40	TBD	Call TI	Call TI	0 to 70	LM 741CN	

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

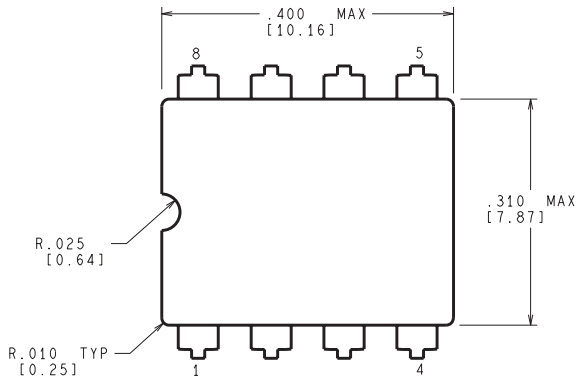
**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

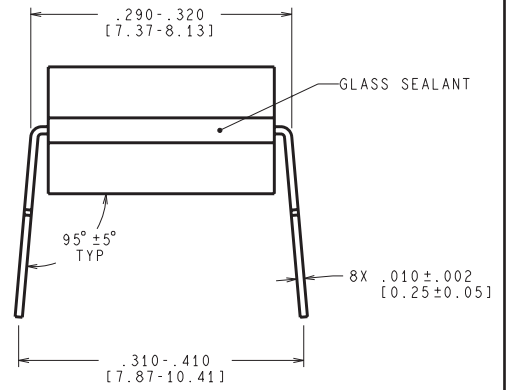
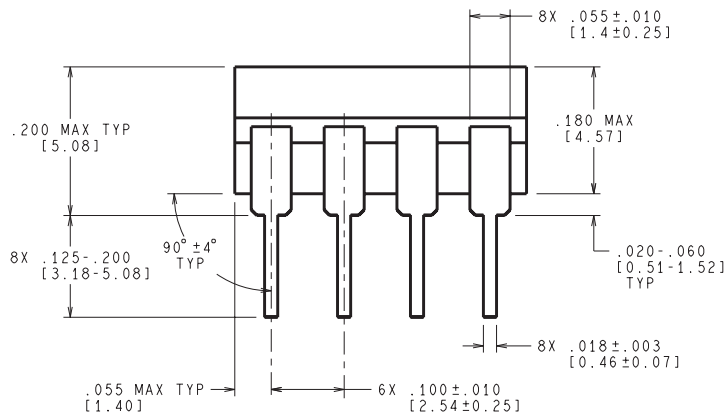
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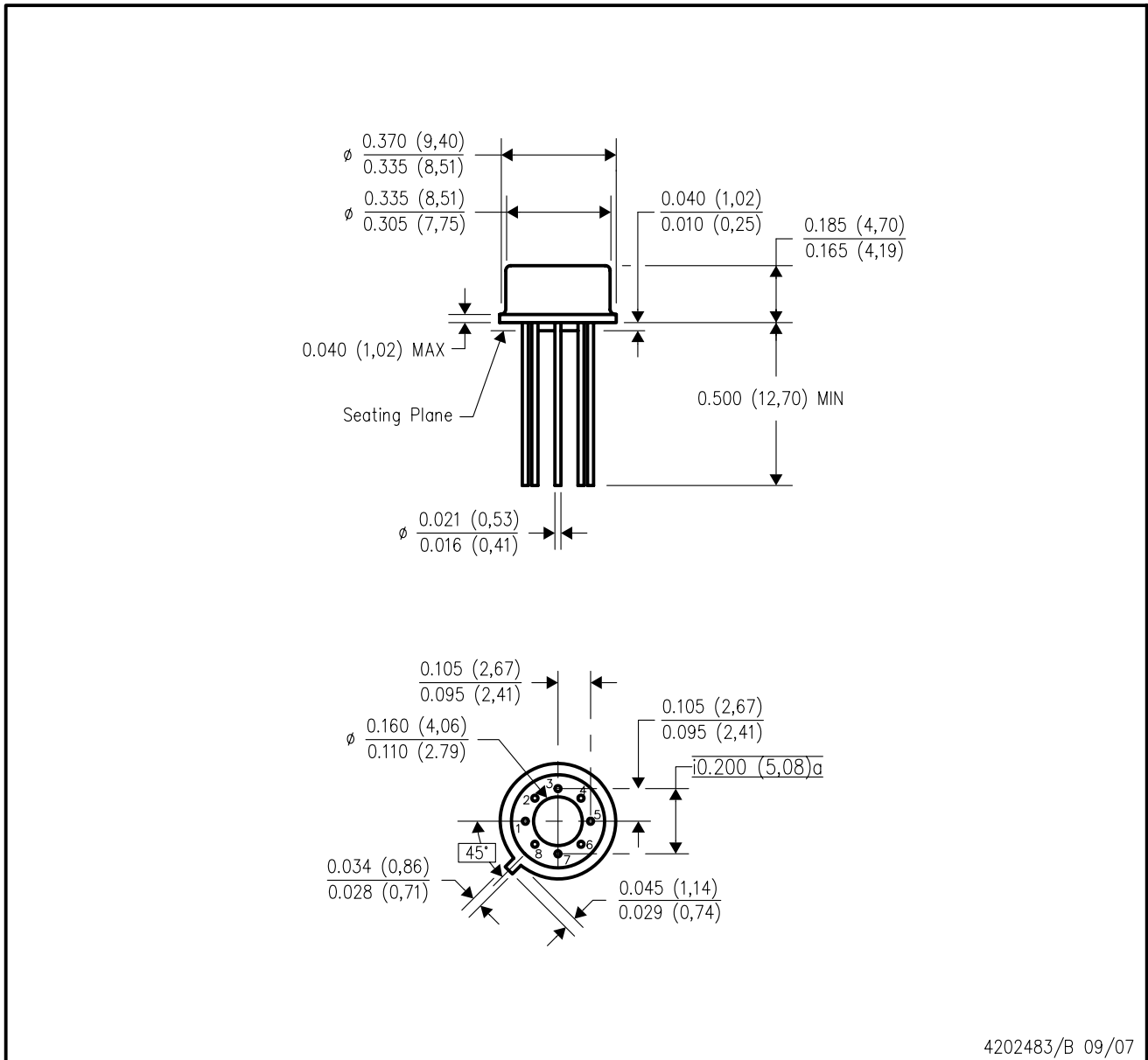


J08A (Rev M)



LMC (O-MBCY-W8)

METAL CYLINDRICAL PACKAGE

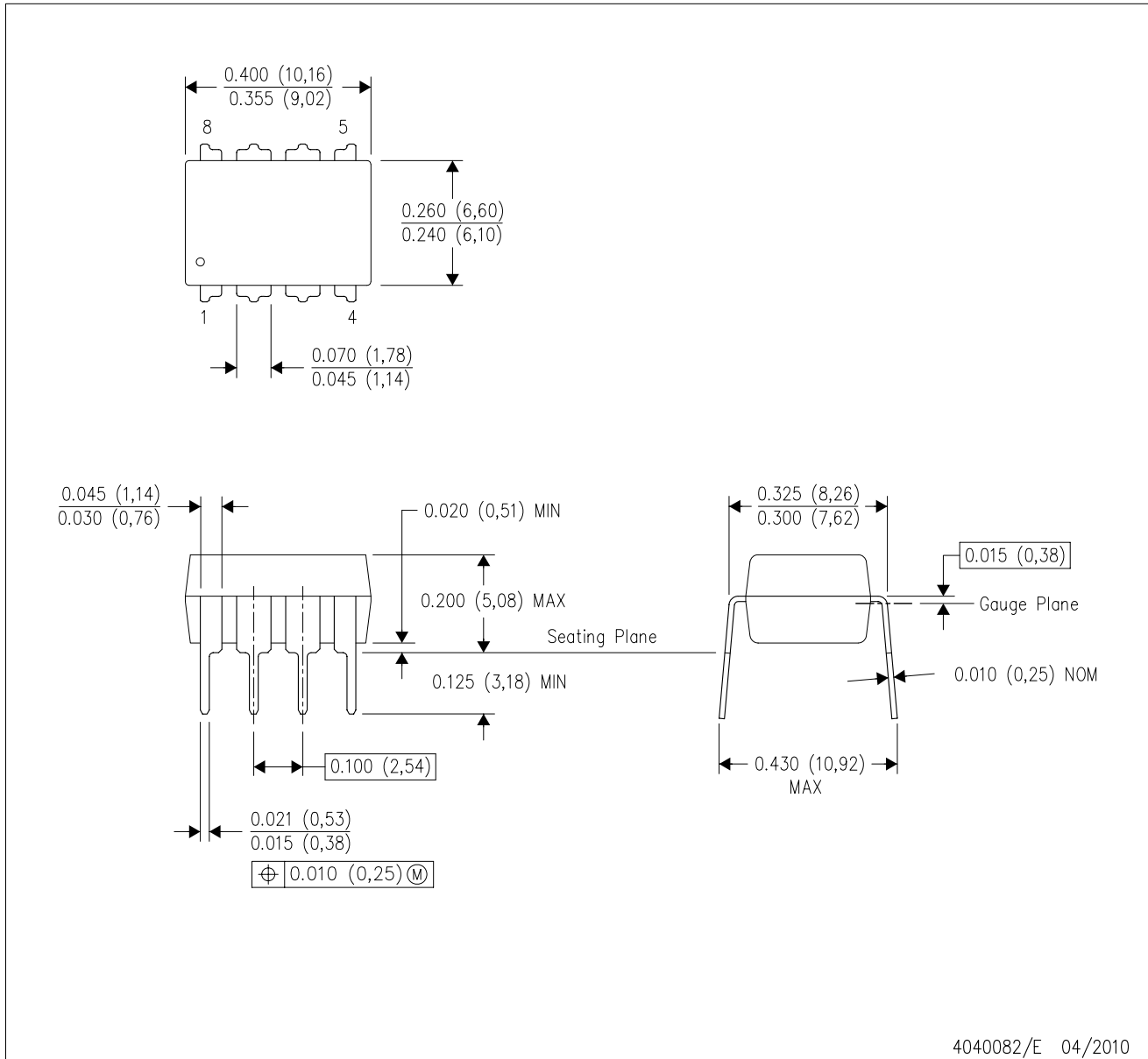


4202483/B 09/07

- NOTES:
- A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Leads in true position within 0.010 (0,25) R @ MMC at seating plane.
  - D. Pin numbers shown for reference only. Numbers may not be marked on package.
  - E. Falls within JEDEC MO-002/TO-99.

P (R-PDIP-T8)

PLASTIC DUAL-IN-LINE PACKAGE



4040082/E 04/2010

- NOTES:
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